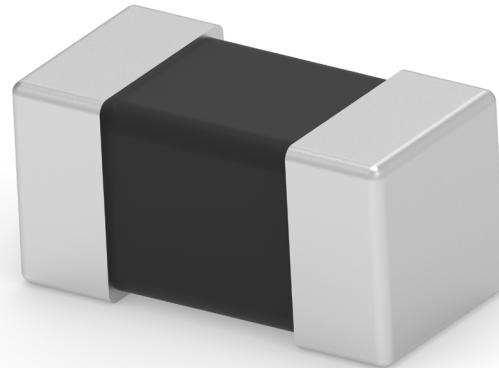


INTRODUCING AUTOMOTIVE GRADE MULTILAYER CHIP BEADS

Type BMC-Q series

- **High moisture resistance**
- **Provides shield against undesirable power loss for DC voltage applications**



TE Connectivity (TE) introduces its automotive grade multilayer chip bead inductors. The BMC-Q series are designed with a monolithic inorganic material construction. The inductors are designed for high and ultra-high current capability and are AEC-Q200 compliant. The inductors are available in 0402, 0603, 0805 and 1204 packaging sizes.

BENEFITS

- Provides shield against undesirable power loss for DC voltage applications
- Prevention against undesirable noise to produce optimum signal transmission
- Viable for use in automotive applications based on multiple size and power requirements availability
- High moisture resistance

FEATURES

- Low DC resistance
- Effective EMI protection
- AEC-Q200 qualified
- Monolithic inorganic material design structure
- Moisture sensitivity level - 2

APPLICATIONS

- Automation controls
- Battery energy storage systems
- Electric vehicle industry
- Robotics

ELECTRICAL

- EMI protection
- Low DC resistance
- High current and ultra high current capability

MECHANICAL

- Designed with monolithic inorganic structure
- Ferrite core

LEARN MORE

- [Automotive grade multilayer chip beads Product Page](#)
- [Automotive grade multilayer chip beads Product Listing Page](#)
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